



SFP28 | XFP

TE Internal #: 2303075-2

XFP, Cage Assembly, Through Hole - Press-Fit Mount, 1 Port, 1 x 1, Pin, Heat Sink Height 6.5 mm [.255 in], Data Rate (Max) 10 Gb/s, XFP

[View on TE.com >](#)

Connectors > Pluggable IO Connectors & Cages > XFP > XFP Cage Assemblies and Kits



Pluggable I/O Product Type: **Cage Assembly**

PCB Mounting Style: **Through Hole - Press-Fit**

Number of Ports: **1**

Port Matrix Configuration: **1 x 1**

Heat Sink Style: **Pin**

[All XFP Cage Assemblies and Kits \(22\)](#)

## Features

### Product Type Features

Form Factor	XFP
Cage Type	Single
Pluggable I/O Product Type	Cage Assembly
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

### Configuration Features

Number of Ports	1
Port Matrix Configuration	1 x 1

### Electrical Characteristics

Data Rate (Max)	10 Gb/s
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### Body Features

Heat Sink Finish	Electroless Nickel
Heat Sink Plating Material	Electroless Nickel
Cage Plating Material	Tin
Heat Sink Style	Pin



Heat Sink Height Class	SAN
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Heat Sink Height	6.5 mm [.255 in]
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### Termination Features

Termination Post & Tail Length	2.05 mm [.08 in]
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Termination Method to Printed Circuit Board	Through Hole - Press-Fit
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### Mechanical Attachment

PCB Mounting Style	Through Hole - Press-Fit
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Connector Mounting Type	Board Mount
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### Housing Features

Cage Material	Copper Alloy
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### Dimensions

Product Width	64.03 mm [2.52 in]
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Product Length	21.7 mm [.854 in]
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### Usage Conditions

Operating Temperature Range	-10 – 70 °C [-14 – 158 °F]
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### Operation/Application

Heat Sink Application	Yes
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Heat Sink Compatible	Yes
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For Use With Pluggable I/O Products	XFP Connector / XFP Cable Plug
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Circuit Application	Signal
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### Packaging Features

Packaging Method	Tray
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### Other

Included Lightpipe	No
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### Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
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EU ELV Directive 2000/53/EC	Compliant
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China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
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EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235)
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Candidate List Declared Against: JUNE  
 2023 (235)  
 Does not contain REACH SVHC

Halogen Content

Low Halogen - Br, Cl, F, I < 900 ppm per  
 homogenous material. Also BFR/CFR/PVC  
 Free

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

### Compatible Parts




TE Part # 1542618-2  
 XFP MSA SAN APPLICATION




TE Part # 1888810-2  
 EMI/Dust Cover, XFP And QSFP

### Also in the Series | XFP



Connector Caps & Covers(1)



Heat Sinks(7)



XFP(25)

### Customers Also Bought



## Documents

### Product Drawings

[XFP KIT W/CAGE, CLIP, HEAT SINK,SAN](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_2303075-2\\_1.2d\\_dxf.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2303075-2\\_1.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_2303075-2\\_1.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

[Application Specification](#)

English